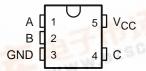
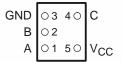
- Available in the Texas Instruments NanoStar[™] and NanoFree[™] Packages
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- Sub 1-V Operable
- Low Power Consumption, 10-µA Max I_{CC}
- **High On-Off Output Voltage Ratio**
- **High Degree of Linearity**
- High Speed Max 0.2 ns ($V_{CC} = 1.8 \text{ V}$, $C_L = 15 pF$
- Low On-State Impedance Typically ≈9 Ω $(V_{CC} = 2.3 \text{ V})$
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW)



YEA OR YZA PACKAGE (BOTTOM VIEW)



description/ordering information

This single analog switch is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

The SN74AUC1G66 can handle both analog and digital signals. It permits signals with amplitudes of up to 3.6-V (peak) to be transmitted in either direction.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

TA	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]	
	NanoStar™ WCSP (DSBGA) – YEA	Tape and reel	SN74AUC1G66YEAR	7.5 U6
-40°C to 85°C	NanoFree™ WCSP (DSBGA) – YZA (Pb-free)	Tape and reel	SN74AUC1G66YZAR	06_
	SOT (SOT-23) – DBV	Tape and reel	SN74AUC1G66DBVR	U66_
	SOT (SC-70) – DCK	Tape and reel	SN74AUC1G66DCKR	U6_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



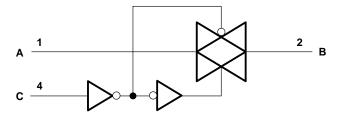


DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site.

FUNCTION TABLE

CONTROL INPUT (C)	SWITCH
L	OFF
Н	ON

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	
Input voltage range, V _I (see Notes 1 and 2)	0.5 V to 3.6 V
Switch I/O voltage range, V _{I/O} (see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Control input clamp current, I _{IK} (V _I < 0)	–50 mA
I/O port diode current, I_{IOK} ($V_{I/O} < 0$ or $V_{I/O} > V_{CC}$)	±50 mA
On-state switch current, I_T ($V_{I/O} = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DBV package	206°C/W
DCK package	252°C/W
YEA/YZA package	154°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to ground unless otherwise specified.
 - 2. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		0.8	2.7	V
		V _{CC} = 0.8 V	Vcc		
V _{IH} High-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		V _{CC} = 0.8 V		0	
VIL	Low-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$		0.35 × V _{CC}	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	
V _{I/O}	I/O port voltage		0	VCC	V
٧ _I	Control input voltage		0	3.6	V
Δt/Δν	Input transition rise or fall rate			20	ns/V
T _A	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS	Vcc	MIN TYPT	MAX	UNIT	
_	On atota quitab registance	$V_I = V_{CC}$ or GND,	Is = 4 mA	1.65 V	10	20	0	
r _{on}	On-state switch resistance	VC = VIH (see Figure 1)	I _S = 8 mA	2.3 V	9	15	Ω	
	Dook on registeres	$V_I = V_{CC}$ to GND,	Is = 4 mA	1.65 V	32	80	Ω	
ron(p)	Peak on resistance	VC = VIH (see Figure 1)	I _S = 8 mA	2.3 V	15	20	77	
1	Off state quitable legislage current	$V_I = V_{CC}$ and $V_O = GI$	$V_I = V_{CC}$ and $V_O = GND$, or			±1	^	
^I S(off)	Off-state switch leakage current	$V_I = GND$ and $V_O = V_O$ $V_C = V_{IL}$ (see Figure 2)		2.7 V		±0.1 [†]	μA t	
IS(on)	On-state switch leakage current	$V_I = V_{CC}$ or GND, V_C	= V _{IH} , V _O = Open	2.7 V		±1	μΑ	
0(011)		(see Figure 3)				±0.1 [†]		
II	Control input current	$V_I = V_{CC}$ or GND		0 to 2.7 V		±5	μΑ	
lcc	Supply current	$V_I = V_{CC}$ or GND, $I_O = 0$		0.8 V to 2.7 V		10	μΑ	
C _{ic}	Control input capacitance			2.5 V	2		pF	
C _{io(off)}	Switch input/output capacitance			2.5 V	3.5	·	pF	
C _{io(on)}	Switch input/output capacitance			2.5 V	7		pF	

[†] All typical values are at $T_A = 25$ °C.

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} =	1.2 V 1 V	V _{CC} =		_	C = 1.8 : 0.15 V		V _{CC} =		UNIT
	(IIVI O1)	(0011 01)	TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t _{pd} ‡	A or B	B or A	0.9		0.3		0.2			0.2		0.1	ns
t _{en}	С	A or B	4.1	0.5	2.6	0.5	1.7	0.5	0.8	1.1	0.5	1	ns
^t dis	С	A or B	5	0.7	3.6	0.5	2.6	0.5	1.7	2.9	0.5	2.2	ns

[‡] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



SN74AUC1G66 SINGLE BILATERAL ANALOG SWITCH

SCES386F - MARCH 2002 - REVISED APRIL 2003

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		c = 1.8 0.15 V		V _{CC} = ± 0.		UNIT
	(INFOT)	(001701)	MIN	TYP	MAX	MIN	MAX	
_{tpd} †	A or B	B or A			0.3		0.3	ns
t _{en}	С	A or B	0.5	1.4	2.3	0.8	1.4	ns
^t dis	С	A or B	0.5	1.7	2.9	0.5	1.5	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74AUC1G66 SINGLE BILATERAL ANALOG SWITCH

SCES386F - MARCH 2002 - REVISED APRIL 2003

analog switch characteristics, $T_A = 25^{\circ}C$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	vcc	TYP	UNIT
				0.8 V	60	
			$C_L = 50 \text{ pF}, R_L = 600 \Omega,$	1.1 V	60	
			f _{in} = sine wave	1.4 V	80	
			(see Figure 5)	1.65 V	120	
Frequency response†	A or B	B or A		2.3 V	170	MHz
(switch ON)	AOIB	BUIA		0.8 V	>500	IVII IZ
			$C_L = 5 \text{ pF}, R_L = 50 \Omega,$	1.1 V	>500	
			f _{in} = sine wave	1.4 V	>500	
			(see Figure 5)	1.65 V	>500	
				2.3 V	>500	
				0.8 V	9	
	С	A or B	$C_L = 50 \text{ pF}, R_L = 600 \Omega,$	1.1 V	14	
Crosstalk (control input to signal output)			f _{in} = 1 MHz (square wave) (see Figure 6)	1.4 V	15	mV
(control input to signal output)				1.65 V	16	
				2.3 V	20	
		B or A		0.8 V	-60	dB
			$C_L = 50 \text{ pF}, R_L = 600 \Omega,$ $f_{\text{in}} = 1 \text{ MHz (sine wave)}$ (see Figure 7)	1.1 V	-60	
				1.4 V	-60	
				1.65 V	-60	
Feed-through attenuation‡	A or B			2.3 V	-60	
(switch OFF)	AOID	BULA		0.8 V	-55	
			$C_L = 5 \text{ pF}, R_L = 50 \Omega,$	1.1 V	-55	
			f _{in} = 1 MHz (sine wave)	1.4 V	– 55	
			(see Figure 7)	1.65 V	-55	
				2.3 V	-55	
				0.8 V	7.5	
			$C_L = 50 \text{ pF}, R_L = 10 \text{ k}\Omega,$	1.1 V	0.16	
	A or B	B or A	f _{in} = 1 kHz (sine wave)	1.4 V	0.04	
Sine-wave distortion			(see Figure 8)	1.65 V	0.03	
				2.3 V	0.02	%
				0.8 V	4.2	/0
			$C_L = 50$ pF, $R_L = 10$ kΩ,	1.1 V	0.2	
	A or B	B or A	f _{in} = 10 kHz (sine wave)	1.4 V	0.03	
			(see Figure 8)	1.65 V	0.02	
				2.3 V	0.02	

[†] Adjust f_{in} voltage to obtain 0 dBm at output. Increase f_{in} frequency until dB meter reads –3 dB. ‡ Adjust f_{in} voltage to obtain 0 dBm at input.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 0.8 V	V _{CC} = 1.2 V	V _{CC} = 1.5 V	V _{CC} = 1.8 V	V _{CC} = 2.5 V	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	3	3	3	3	3	pF



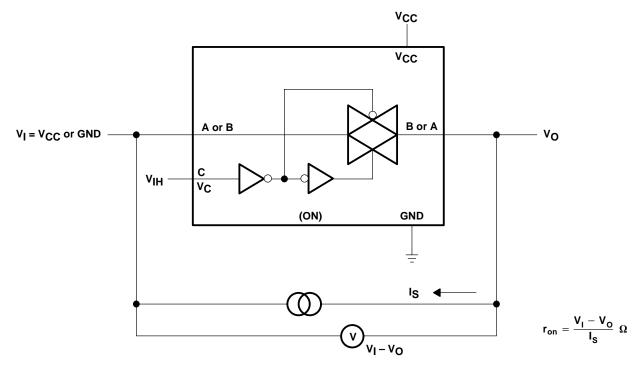


Figure 1. On-State Resistance Test Circuit

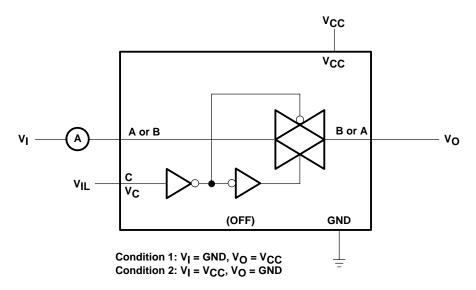


Figure 2. Off-State Switch Leakage-Current Test Circuit



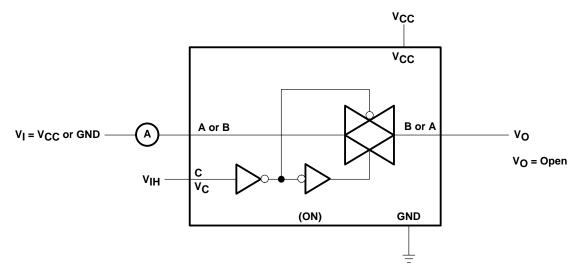
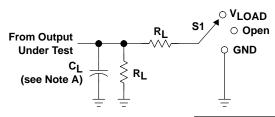


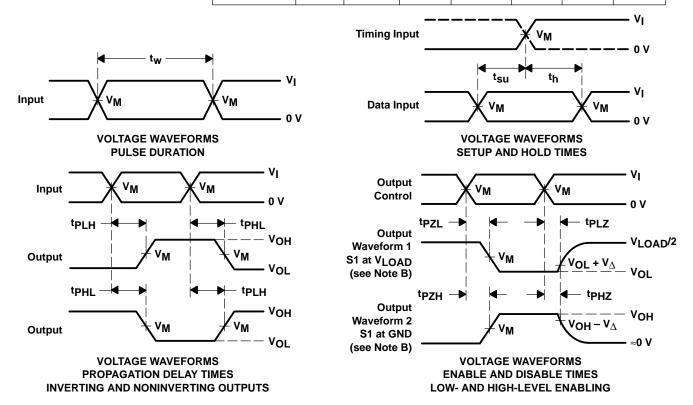
Figure 3. On-State Leakage-Current Test Circuit



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

LOAD CIRCUIT

.,	INPUTS		.,			_	.,
VCC	VI	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
0.8 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	2 k Ω	0.1 V
1.2 V \pm 0.1 V	VCC	≤2 ns	V _{CC} /2	2×VCC	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	2 k Ω	0.1 V
1.8 V ± 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	2 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	2 k Ω	0.15 V
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, slew rate \geq 1 V/ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms



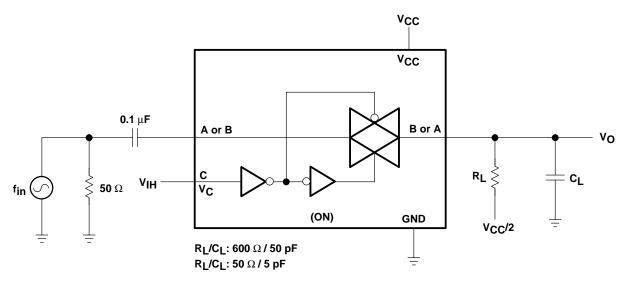


Figure 5. Frequency Response (Switch ON)

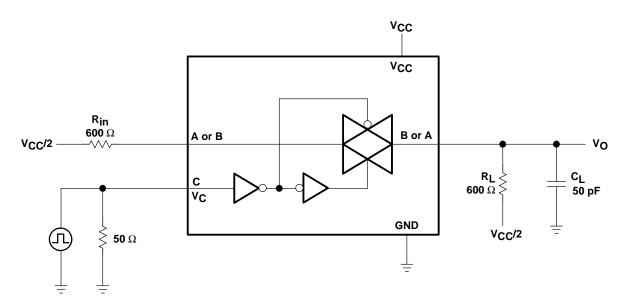


Figure 6. Crosstalk (Control Input – Switch Output)

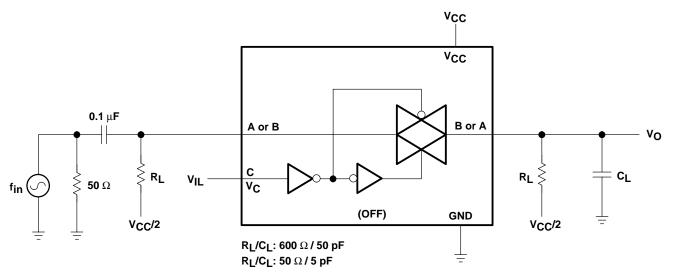


Figure 7. Feed Through, Switch Off

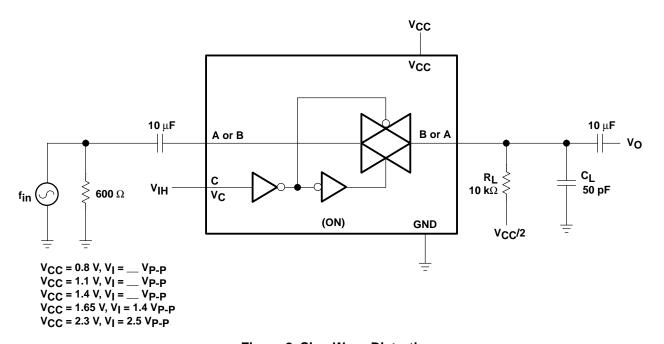
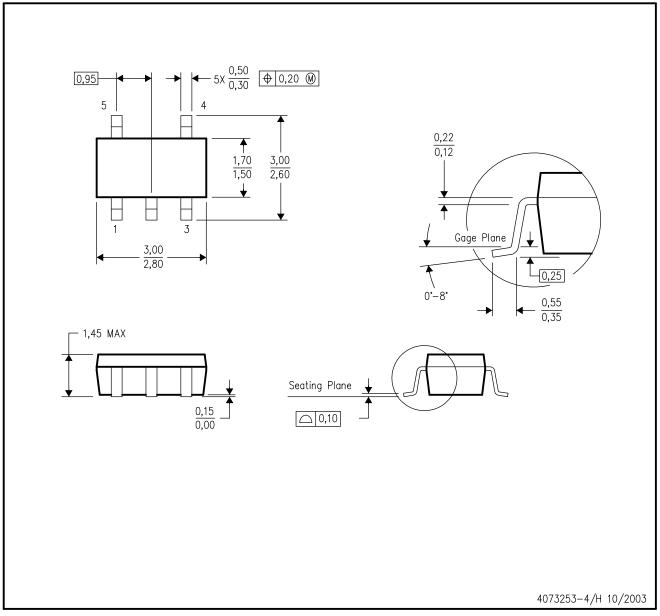


Figure 8. Sine-Wave Distortion



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



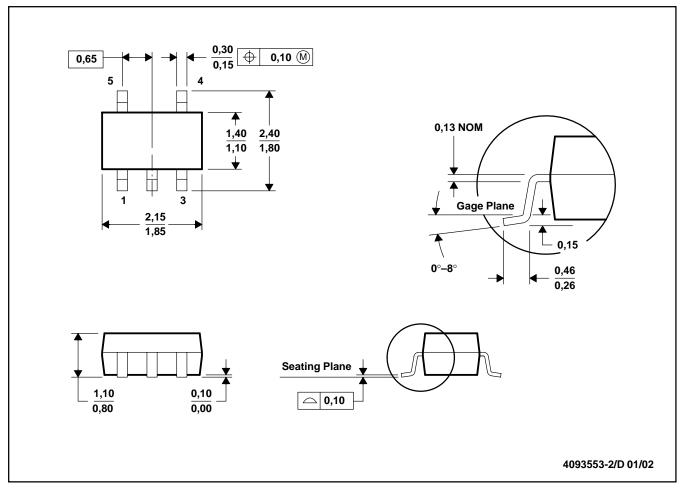
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-178 Variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

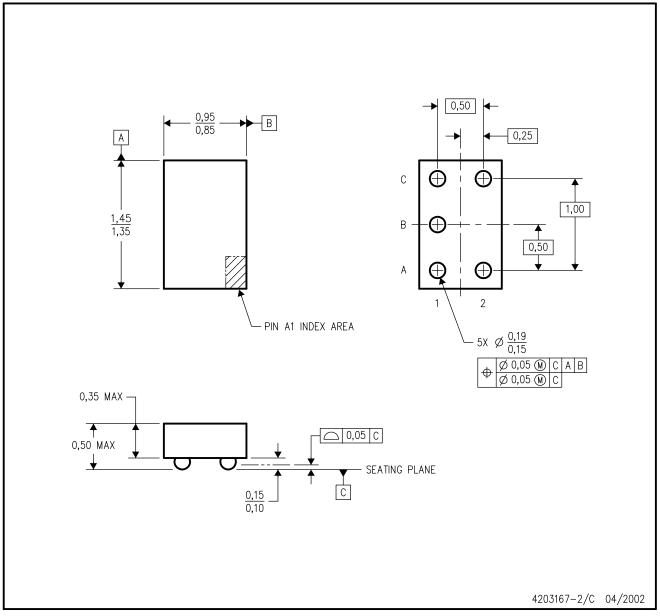


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES:

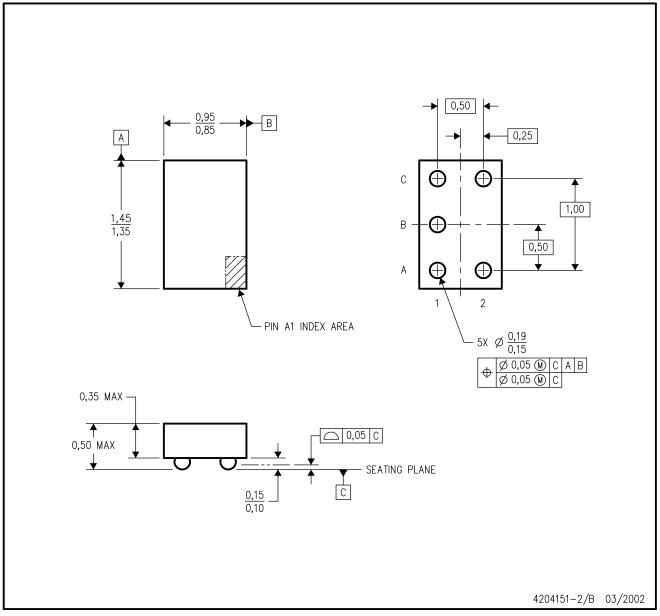
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. NanoStar™ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.



YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



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